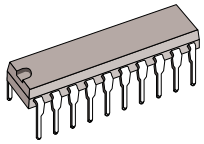
SGS-THOMSON MICROELECTRONICS

ETC5064/64-X
ETC5067/67-X

SERIAL INTERFACE CODEC/FILTER WITH RECEIVE POWER AMPLIFIER

- COMPLETE CODEC AND FILTERING SYSTEM INCLUDING :
  - Transmit high-pass and low-pass filtering.
  - Receive low-pass filter with sin x/x correction.
  - Active RC noise filter.
  - μ-law or A-law compatible CODER and DECODER.
  - Internal precision voltage reference.
  - Serial I/O interface.
  - Internal auto-zero circuitry.
  - Receive push-pull power amplifiers.
- μ-LAW ETC5064
- A-LAW ETC5067
- MEETS OR EXCEEDS ALL D3/D4 AND CCITT SPECIFICATIONS.
- ± 5 V OPERATION.
- LOW OPERATING POWER-TYPICALLY 70 mW
- POWER-DOWN STANDBY MODE-TYPICALLY 3 mW
- AUTOMATIC POWER DOWN
- TTL OR CMOS COMPATIBLE DIGITAL INTERFACES
- MAXIMIZES LINE INTERFACE CARD CIRCUIT DENSITY
- 0°C TO 70°C OPERATION: ETC5064/67
- –40°C TO 85°C OPERATION: ETC5064-X/67-X



DIP20
(Plastic) N

ORDERING NUMBERS:
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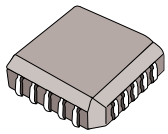
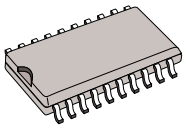
ETC5064N-X
ETC5067N
ETC5067N-X



PLCC20
FN

ORDERING NUMBERS:
ETC5064FN
ETC5064FN-X
ETC5067FN
ETC5067FN-X



SO20
D

ORDERING NUMBERS:
ETC5064D
ETC5064D-X
ETC5067D
ETC5067D-X

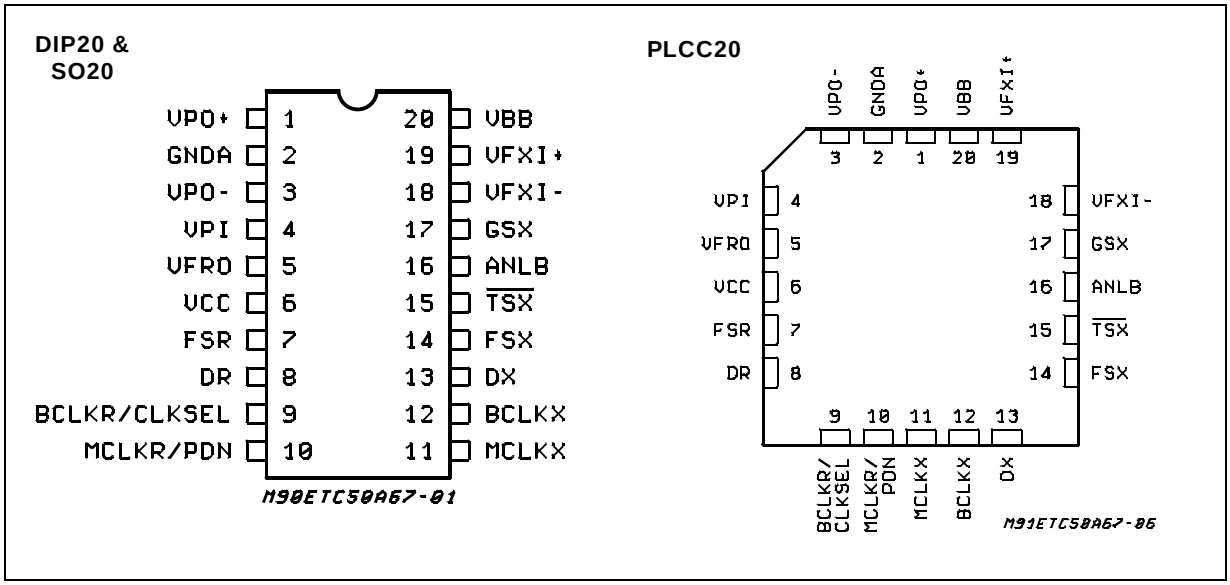
DESCRIPTION

The ETC5064 (μ-law), ETC5067 (A-law) are monolithic PCM CODEC/FILTERS utilizing the A/D and D/A conversion architecture shown in the Block Diagrams and a serial PCM interface. The devices are fabricated using double-poly CMOS process.

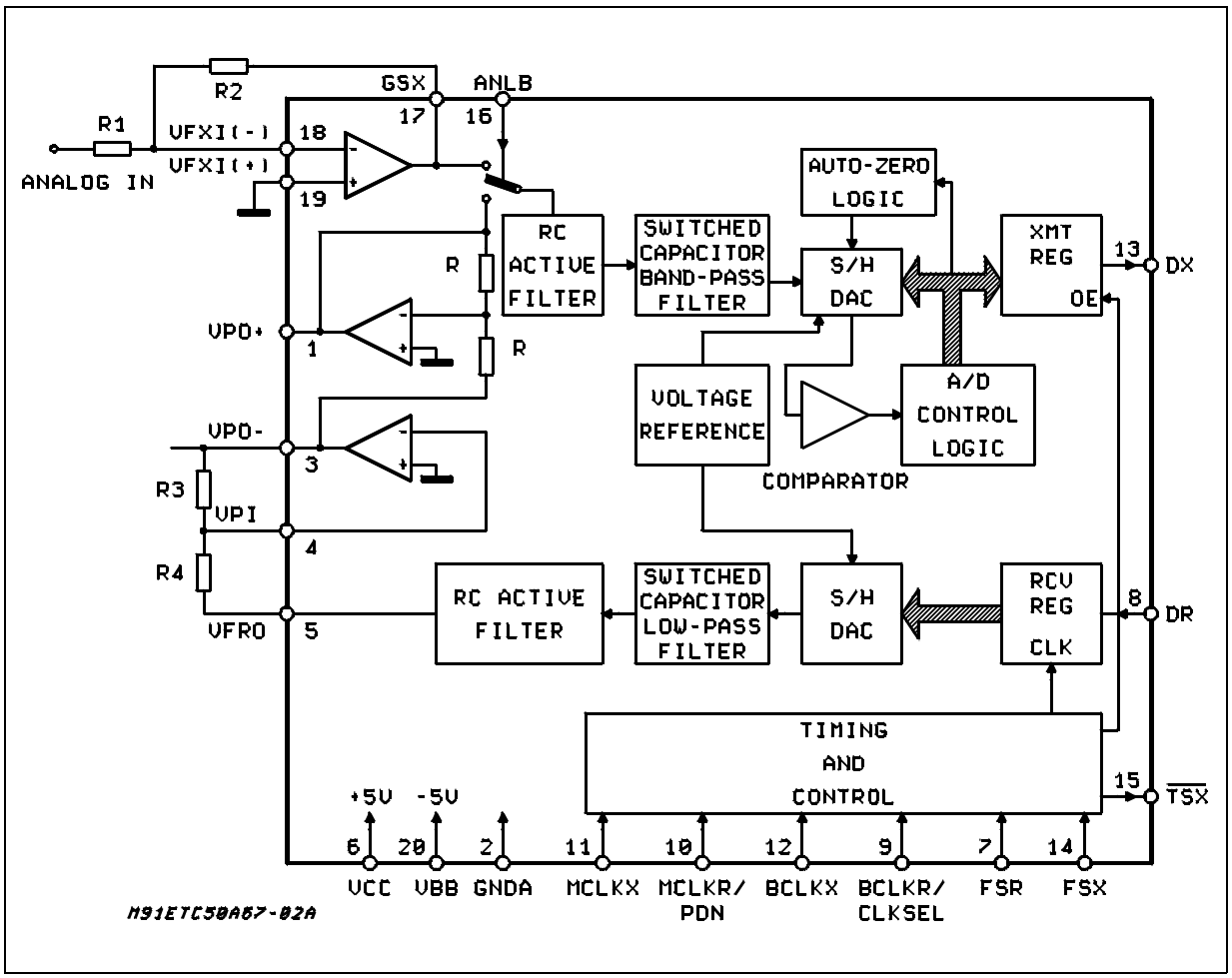
Similar to the ETC505X family, these devices feature an additional Receive Power Amplifier to provide push-pull balanced output drive capability. The receive gain can be adjusted by means of two external resistors for an output level of up to ± 6.6 V across a balanced 600Ω load.

Also included is an Analog Loopback switch and $\overline{TS}_X$ output.

PIN CONNECTIONS (Top views)



BLOCK DIAGRAM (ETC5064 - ETC5064-X - ETC5067 - ETC5067-X)



PIN DESCRIPTION

Name	Pin Type (*)	N	Description
VPO^+	O	1	The Non-inverting Output of the Receive Power Amplifier
GNDA	GND	2	Analog Ground. All signals are referenced to this pin.
VPO^-	O	3	The Inverting Output of the Receive Power Amplifier
VPI	I	4	Inverting Input to the Receive Power Amplifier. Also powers down both amplifiers when connected to V_{BB}.
VF_RO	O	5	Analog Output of the Receive Filter.
V_{CC}	S	6	Positive Power Supply Pin. V_{CC} = +5V ±5%
FS_R	I	7	Receive Frame Sync Pulse which enable $BCLK_R$ to shift PCM data into D_R. FS_R is an 8KHz pulse train. See figures 1 and 2 for timing details.
D_R	I	8	Receive Data Input. PCM data is shifted into D_R following the FS_R leading edge
$BCLK_R$/CLKSEL	I	9	The bit Clock which shifts data into D_R after the FS_R leading edge. May vary from 64KHz to 2.048MHz. Alternatively, may be a logic input which selects either 1.536MHz/1.544MHz or 2.048MHz for master clock in synchronous mode and $BCLK_X$ is used for both transmit and receive directions (see table 1). This input has an internal pull-up.
$MCKL_R$/PDN	I	10	Receive Master Clock. Must be 1.536MHz, 1.544MHz or 2.048MHz. May be asynchronous with $MCLK_X$, but should be synchronous with $MCLK_X$ for best performance. When $MCLK_R$ is connected continuously low, $MCLK_X$ is selected for all internal timing. When $MCLK_R$ is connected continuously high, the device is powered down.
$MCLK_X$	I	11	Transmit Master Clock. Must be 1.536MHz, 1.544MHz or 2.048MHz. May be asynchronous with $MCLK_R$.
$BCLK_X$	I	12	The bit clock which shifts out the PCM data on D_X. May vary from 64KHz to 2.048MHz, but must be synchronous with $MCLK_X$.
D_X	O	13	The TRI-STATE®PCM data output which is enabled by FS_X.
FS_X	I	14	Transmit frame sync pulse input which enables $BCLK_X$ to shift out the PCM data on D_X. FS_X is an 8KHz pulse train. See figures 1 and 2 for timing details.
$\overline{TS_X}$	O	15	Open drain output which pulses low during the encoder time slot. Must to be grounded if not used.
ANLB	I	16	Analog Loopback Control Input. Must be set to logic '0' for normal operation. When pulled to logic '1', the transmit filter input is disconnected from the output of the transmit preamplifier and connected to the VPO^+ output of the receive power amplifier.
GS_X	O	17	Analog output of the transmit input amplifier. Used to set gain externally.
VF_XI^-	I	18	Inverting input of the transmit input amplifier.
VF_XI^+	I	19	Non-inverting input of the transmit input amplifier.
V_{BB}	S	20	Negative Power Supply Pin. V_{BB} = -5V ±5%

(*) I: Input, O: Output, S: Power Supply.
TRI-STATE® is a trademark of National Semiconductor Corp.

FUNCTIONAL DESCRIPTION

POWER-UP

When power is first applied, power-on reset circuitry initializes the device and places it into the power-down mode. All non-essential circuits are deactivated and the D_X and VF_RO outputs are put in high impedance states. To power-up the device, a logical low level or clock must be applied to the $MCLK_R$/PDN pin and FS_X and/or FS_R pulses must be present. Thus 2 power-down control modes are available. The first is to pull the $MCLK_R$/PDN pin high; the alternative is to hold both FS_X and FS_R inputs continuously low. The device will power-down approximately 2 ms after the last FS_X pulse. The TRI-STATE PCM data output, D_X, will remain in the high impedance state until the second FS_X pulse.

SYNCHRONOUS OPERATION

For synchronous operation, the same master clock and bit clock should be used for both the transmit and receive directions. In this mode, a clock must be applied to $MCLK_X$ and the $MCLK_R$/PDN pin can be used as a power-down control. A low level on $MCLK_R$/PDN powers up the device and a high level powers down the device. In either case, MCLKX will be selected as the master clock for both the transmit and receive circuits. A bit clock must also be applied to $BCLK_X$ and the BCL_R/CLKSEL can be used to select the proper internal divider for a master clock of 1.536 MHz, 1.544 MHz or 2.048 MHz. For 1.544 MHz operation, the device automatically compensates for the 193 rd clock pulse each frame.

With a fixed level on the $BCLK_R$/CKSEL pin, $BCLK_X$ will be selected as the bit clock for both the transmit and receive directions. Table 1 indicates the frequencies of operation which can be selected, depending on the state of $BCLK_R$/CLKSEL. In this synchronous mode, the bit clock, $BCLK_X$, may be from 64 kHz to 2.048 MHz, but must be synchronous with $MCLK_X$.

Table 1: Selection of Master Clock Frequencies.

BCLKR/CLKSEL	Master Clock Frequency Selected	
	ETC5067 ETC5067-X	ETC5064 ETC5064-X
Clocked	2.048MHz	1.536MHz or 1.544MHz
0	1.536MHz or 1.544MHz	2.048MHz
1 (or open circuit)	2.048MHz	1.536MHz or 1.544MHz

Each FS_X pulse begins the encoding cycle and the PCM data from the previous encode cycle is shift out of the enabled D_X output on the positive edge of $BCLK_X$. After 8 bit clock periods, the TRISTATE D_X output is returned to a high impedance state. With an FS_R pulse, PCM data is latched via the D_R input on the negative edge of $BCLK_X$ (or on $BCKL_R$ if running). FS_X and FS_R must be synchronous with MCLKX/$_R$.

ASYNCHRONOUS OPERATION

For asynchronous operation, separate transmit and receive clocks may be applied. $MCLK_X$ and $MCLK_R$ must be 2.048 MHz for the ETC5067 or 1.536 MHz, 1.544 MHz for the ETC5064, and need not be synchronous. For best transmission performance, however, $MCLK_R$ should be synchronous with $MCLK_X$, which is easily achieved by applying only static logic levels to the $MCLK_R$/PDN pin. This will automatically connect $MCLK_X$ to all internal $MCLK_R$ functions (see pin description). For 1.544 MHz operation, the device automatically compensates for the 193rd clock pulse each frame. FS_X starts each encoding cycle and must be synchronous with $MCLK_X$ and $BCLK_X$. FS_R starts each decoding cycle and must be synchronous with $BCLK_R$. $BCLK_R$ must be a clock, the logic levels shown in Table 1 are not valid in asynchronous mode. $BCLK_X$ and $BCLK_R$ may operate from 64kHz to 2.048 MHz.

SHORT FRAME SYNC OPERATION

The device can utilize either a short frame sync pulse or a long frame sync pulse. Upon power initialization, the device assumes a short frame mode. In this mode, both frame sync pulses. FS_X and FS_R, must be one bit clock period long, with timing relationships specified in figure 2. With FS_X high during a falling edge of $BCLK_R$, the next rising edge of $BCLK_X$ enables the D_X TRI-STATE output buffer, which will output the sign bit. The following seven rising edges clock out the remaining seven bits, and the next falling edge disables the D_X output. With FS_R high during a falling edge of $BCLK_R$ ($BCLK_X$ in synchronous mode), the next falling edge of $BCLK_R$ latches in the sign bit. The following seven falling edges latch in the seven remaining bits. Both devices may utilize the short frame sync pulse in synchronous or asynchronous operating mode.

LONG FRAME SYNC OPERATION

To use the long frame mode, both the frame sync pulses, FS_X and FS_R, must be three or more bit clock periods long, with timing relationships specified in figure 3. Based on the transmit frame sync FS_X, the device will sense whether short or long frame sync

pulses are being used. For 64 kHz operation, the frame sync pulses must be kept low for a minimum of 160 ns (see Fig 1). The D_X TRI-STATE output buffer is enabled with the rising edge of FS_X or the rising edge of $BCLK_X$, whichever comes later, and the first bit clocked out is the sign bit. The following seven $BCLK_X$ rising edges clock out the remaining seven bits. The D_X output is disabled by the falling $BCLK_X$ edge following the eighth rising edge, or by FS_X going low, whichever comes later. A rising edge on the receive frame sync pulse, FS_R, will cause the PCM data at D_R to be latched in on the next eight falling edges of $BCLK_R$ ($BCLK_X$ in synchronous mode). Both devices may utilize the long frame sync pulse in synchronous or asynchronous mode.

TRANSMIT SECTION

The transmit section input is an operational amplifier with provision for gain adjustment using two external resistors, see figure 4. The low noise and wide bandwidth allow gains in excess of 20 dB across the audio passband to be realized. The op amp drives a unity gain filter consisting of RC active pre-filter, followed by an eighth order switched-capacitor bandpass filter directly drives the encoder sample-and-hold circuit. The A/D is of companding type according to A-law (ETC5067 and ETC5067-X) or µ-law (ETC5064 and ETC5064-X) coding conventions. A precision voltage reference is trimmed in manufacturing to provide an input over load (t_{MAX}) of nominally 2.5V peak (see table of Transmission Characteristics). The FS_X frame sync pulse controls the sampling of the filer output, and then the successive-approximation encoding cycle begins. The 8-bit code is then loaded into a buffer and shifted out through D_X at the next FS_X pulse. the total encoding delay will be approximately 165 µs (due to the transmit filter) plus 125µs (due to encoding delay), which totals 290µs. Any offset voltage due to the filters or comparator is cancelled by sign bit integration.

RECEIVE SECTION

The receive section consist of an expanding DAC which drives a fifth order switched-capacitor low pass filter clocked at 256kHz. The decoder is A-law (ETC5067 and ETC5067-X) or µ–law (ETC5064 and ETC5064-X) and the 5 th order low pass filter corrects for the sin x/x attenuation due to the 8kHz sample and hold. The filter is then followed by a 2 nd order RC active post-filter and power amplifier capable of driving a 600Ω load to a level of 7.2dBm. The receive section is unity-gain. Upon the occurence of FS_R, the data at the D_R input is clocked in on the falling edge of the next eight $BCLK_R$ ($BCKL_X$) periods. At the end of the decoder time slot, the decoding cycle begins, and 10µs later the decoder DAC output is updated. The total decoder delay is about10µs (decoder up-date) plus 110µs (filter delay) plus 62.5µs (1/2 frame), which gives approximately 180µs.

RECEIVE POWER AMPLIFIERS

Two inverting mode power amplifiers are provided for directly driving a matched line interface transformer. The gain of the first power amplifier can be adjusted to boost the ± 2.5V peak output signal from the receive filter up ± 3.3V peak into an unbalanced 300Ω load, or ±4.0V into an unbalanced 15kΩ load. The second power amplifier is internally connected in unity-gain inverting mode to give 6dB of signal gain for balanced loads. Maximum power transfer to a 600Ω subscriber line termination is obtained by differientially driving a balanced transformer with a $\sqrt{2}$: 1 turns ratio, as shown in figure 4. A total peak power of 15.6dBm can be delivered to the load plus termination. Both power amplifier can be powered down independently from the PDN input by connecting the VPI input to V_{BB} saving approximately 12 mW of power.

ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V_{CC}	V_{CC} to GNDA	7	V
V_{BB}	V_{BB} to GNDA	-7	V
V_{IN}, V_{OUT}	Voltage at any Analog Input or Output	V_{CC} +0.3 to V_{BB} -0.3	V
	Voltage at any Digital Input or Output	V_{CC} +0.3 to GNDA -0.3	V
T_{oper}	Operating Temperature Range: **ETC5064/67** **ETC5064-X/67-X**	-25 to +125 -40 to +125	°C °C
T_{stg}	Storage Temperature Range	-65 to +150	°C
	Lead Temperature (soldering, 10 seconds)	300	°C

ELECTRICAL OPERATING CHARACTERISTICS

V_{CC} = 5.0V ±5%, V_{BB} = -5V ±5%, GNDA = 0V, T_A = 0°C to 70°C (ETC5064-X/67-X: T_A = –40°C to 85°), unless otherwise noted; typical characteristics specified at V_{CC} = 5.0V, V_{BB} =-5.0V, T_A = 25°C; all signals are referenced to GNDA.

DIGITAL INTERFACE (All devices)

Symbol	Parameter	Min.	Typ.	Max.	Unit
V_{IL}	Input Low Voltage			0.6	V
V_{IH}	Input High Voltage	2.2			V
V_{OL}	Output Low Voltage I_L = 3.2 mA D_X I_L = 3.2 mA, Open Drain $\overline{TS_X}$			 0.4 0.4	 V V
V_{OH}	Output High Voltage IH = 3.2 mA D_X	 2.4			 V
I_{IL}	Input Low Current (GNDA ≤ V_{IN} ≤ V_{IL})all digital inputs Except $BCLK_R$	– 10		10	µA
I_{IH}	Input High Current (V_{IH} ≤ V_{IN} ≤ V_{CC}) Except ANLB	– 10		10	µA
I_{OZ}	Output Current in High Impedance State (TRI-STATE) (GNDA ≤ V_O ≤ V_{CC}) D_X	– 10		10	µA

ANALOG INTERFACE WITH TRANSMIT INPUT AMPLIFIER (all devices)

Symbol	Parameter	Min.	Typ.	Max.	Unit
I_IXA	Input Leakage Current $VFxI^+$ or $VFxI^-$ (– 2.5 V ≤ V ≤ + 2.5 V)	– 200		200	nA
R_IXA	Input Resistance VF_XI^+ or VF_XI^- (– 2.5 V ≤ V ≤ + 2.5 V)	10			MΩ
R_OXA	Output Resistance (closed loop, unity gain)		1	3	Ω
R_LXA	Load Resistance GS_X	10			kΩ
C_LXA	Load Capacitance GS_X			50	pF
V_OXA	Output Dynamic Range (R_L ≥ 10 kΩ) GS_X	– 2.8		+2.8	V
A_VXA	Voltage Gain (VF_XI^+ to GS_X)	5000			V/V
F_UXA	Unity Gain Bandwidth	1	2		MHz
V_{OS}XA	Offset Voltage	– 20		20	mV
V_{CM}XA	Common-mode Voltage	– 2.5		2.5	V
CMRRXA	Common-mode Rejection Ratio	60			dB
PSRRXA	Power Supply Rejection Ratio	60			dB

ANALOG INTERFACE WITH RECEIVE FILTER (all devices)

Symbol	Parameter	Min.	Typ.	Max.	Unit
R_ORF	Output Resistance VF_RO		1	3	Ω
R_LRF	Load Resistance (VF_RO = ± 2.5 V)	10			kΩ
C_LRF	Load Capacitance			25	pF
VOS_RO	Output DC Offset Voltage	– 200		200	mV

ELECTRICAL OPERATING CHARACTERISTICS (Continued)

ANALOG INTERFACE WITH POWER AMPLIFIERS (all devices)

Symbol	Parameter	Min.	Typ.	Max.	Unit
IPI	Input Leakage Current (– 1.0 V ≤ VPI ≤ 1.0 V)	– 100		100	nA
RIPI	Input Resistance (– 1.0 ≤ VPI ≤ 1.0 V)	10			MΩ
VIOS	Input Offset Voltage	– 25		25	mV
ROP	Output Resistance (inverting unity–gain at VPO^+ or VPO^-)		1		Ω
F_C	Unity–gain Bandwidth, Open Loop (VPO^-)		400		kHz
C_LP	Load Capacitance (VPO^+ or VPO^- to GNDA) $R_L \geq 1500\ \Omega$ $R_L = 600\ \Omega$ $R_L = 300\ \Omega$			 100 500 1000	pF
GAp^+	Gain VPO^- to VPO^+ to GNDA, Level at VPO^- = 1. 77 Vrms (+ 3 dBmO)		– 1		V/V
PSRRp	Power Supply Rejection of V_{CC} or V_{BB} (VPO^- connected to VPI) 0 kHz – 4 kHz 0 kHz – 50 kHz	 60 36			dB

POWER DISSIPATION (all devices)

Symbol	Parameter	Min.	Typ.	Max.	Unit
$I_{CC}0$	Power-down Current at **ETC6064/67** **ETC5064-X/67-X**		0.5 0.5	1.5	mA mA
$I_{BB}0$	Power-down Current at **ETC6064/67** **ETC5064-X/67-X**		0.05 0.05	0.3 0.4	mA mA
$I_{CC}1$	Active Current at **ETC6064/67** **ETC5064-X/67-X**		7.0 7.0	10.0 12.0	mA mA
$I_{BB}1$	Active Current at **ETC6064/67** **ETC5064-X/67-X**		7.0 7.0	10.0 12.0	mA mA

All TIMING SPECIFICATIONS

Symbol	Parameter	Min.	Typ.	Max.	Unit
$1/t_{PM}$	Frequency of master clocks $MCLK_X$ and $MCLK_R$ Depends on the device used and the $BCLK_R$/CLKSEL Pin		1.536 2.048 1.544		MHz
t_{WMH}	Width of Master Clock High $MCLK_X$ and $MCLK_R$	160			ns
t_{WML}	Width of Master Clock Low $MCLK_X$ and $MCLK_R$	160			ns
t_{RM}	Rise Time of Master Clock $MCLK_X$ and $MCLK_R$			50	ns
t_{FM}	Fall Time of Master Clock $MCLK_X$ and $MCLK_R$			50	ns
t_{PB}	Period of Bit Clock	485	488	15.725	ns
t_{WBH}	Width of Bit Clock High (V_{IH} = 2.2 V)	160			ns
t_{WBL}	Width of Bit Clock Low (V_{IL} = 0.6 V)	160			ns
t_{RB}	Rise Time of Bit Clock (t_{PB} = 488 ns)			50	ns
t_{FB}	Fall Time of Bit Clock (t_{PB} = 488 ns)			50	ns
t_{SBFM}	Set-up time from $BCLK_X$ high to $MCLK_X$ falling edge. (first bit clock after the leading edge of FS_X)	100			ns
t_{HBF}	Holding Time from Bit Clock Low to the Frame Sync (long frame only)	0			ns
t_{SFB}	Set-up Time from Frame Sync to Bit Clock (long frame only)	80			ns
t_{HBFI}	Hold Time from 3rd Period of Bit Clock Low to Frame Sync (long frame only) FS_X or FS_R	100			ns
t_{DZF}	Delay Time to valid data from FS_X or $BCLK_X$, whichever comes later and delay time from FSX to data output disabled (C_L = 0 pF to 150 pF)	20		165	ns
t_{DBD}	Delay Time from $BCLK_X$ high to data valid (load = 150 pF plus 2 LSTTL loads)	0		150	ns
t_{DZC}	Delay Time from $BCLK_X$ low to data output disabled	50		165	ns
t_{SDB}	Set-up Time from D_R valid to $BCLK_{R/X}$ low	50			ns
t_{HBD}	Hold Time from $BCLK_{R/X}$ low to D_R invalid	50			ns
t_{HOLD}	Holding Time from Bit Clock High to Frame Sync (short frame only)	0			ns
t_{SF}	Set-up Time from $FS_{X/R}$ to $BCLK_{X/R}$ Low (short frame sync pulse) - Note 1	80			ns
t_{HF}	Hold Time from $BCLK_{X/R}$ Low to $FS_{X/R}$ Low (short frame sync pulse) - Note 1	100			ns
t_{XDP}	Delay Time to TS_X low (load = 150 pF plus 2 LSTTI loads)			140	ns
t_{WFL}	Minimum Width of the Frame Sync Pulse (low level) (64 bit/s operating mode)	160			ns

Note : 1.For short frame sync timing. FS_X and FS_R must go high while their respective bit clocks are high.

Figure 1 : 64 k bits/s TIMING DIAGRAM. (see next page for complete timing)

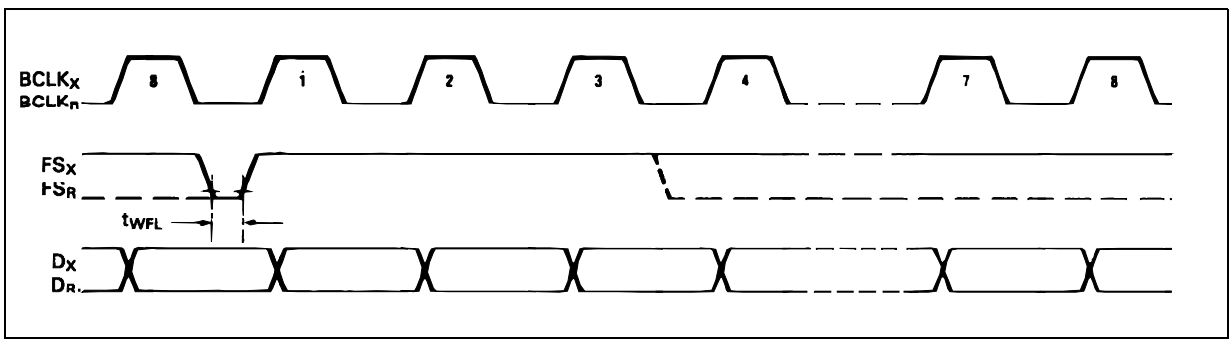


Figure 2 : Short Frame Sync Timing.

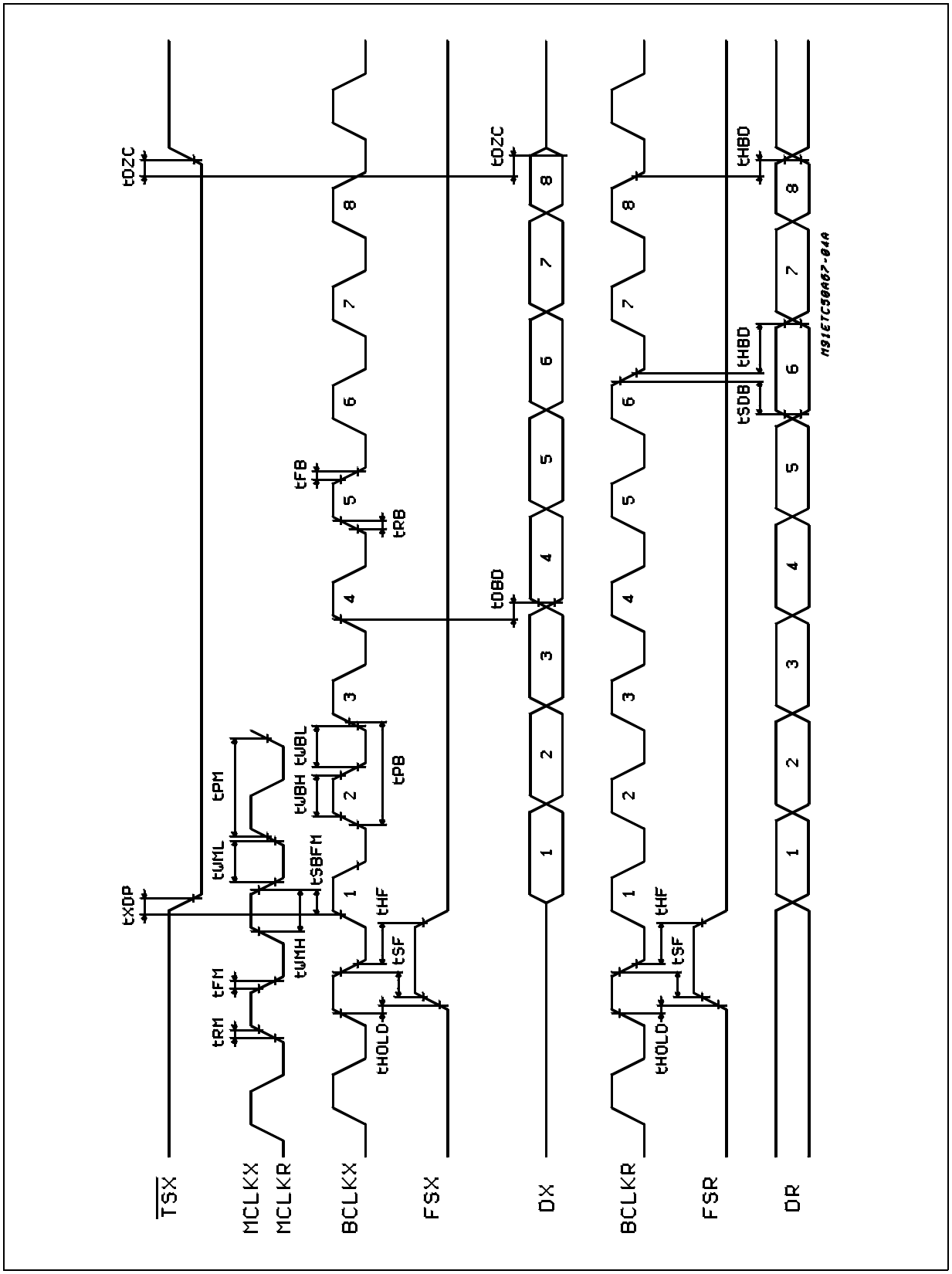
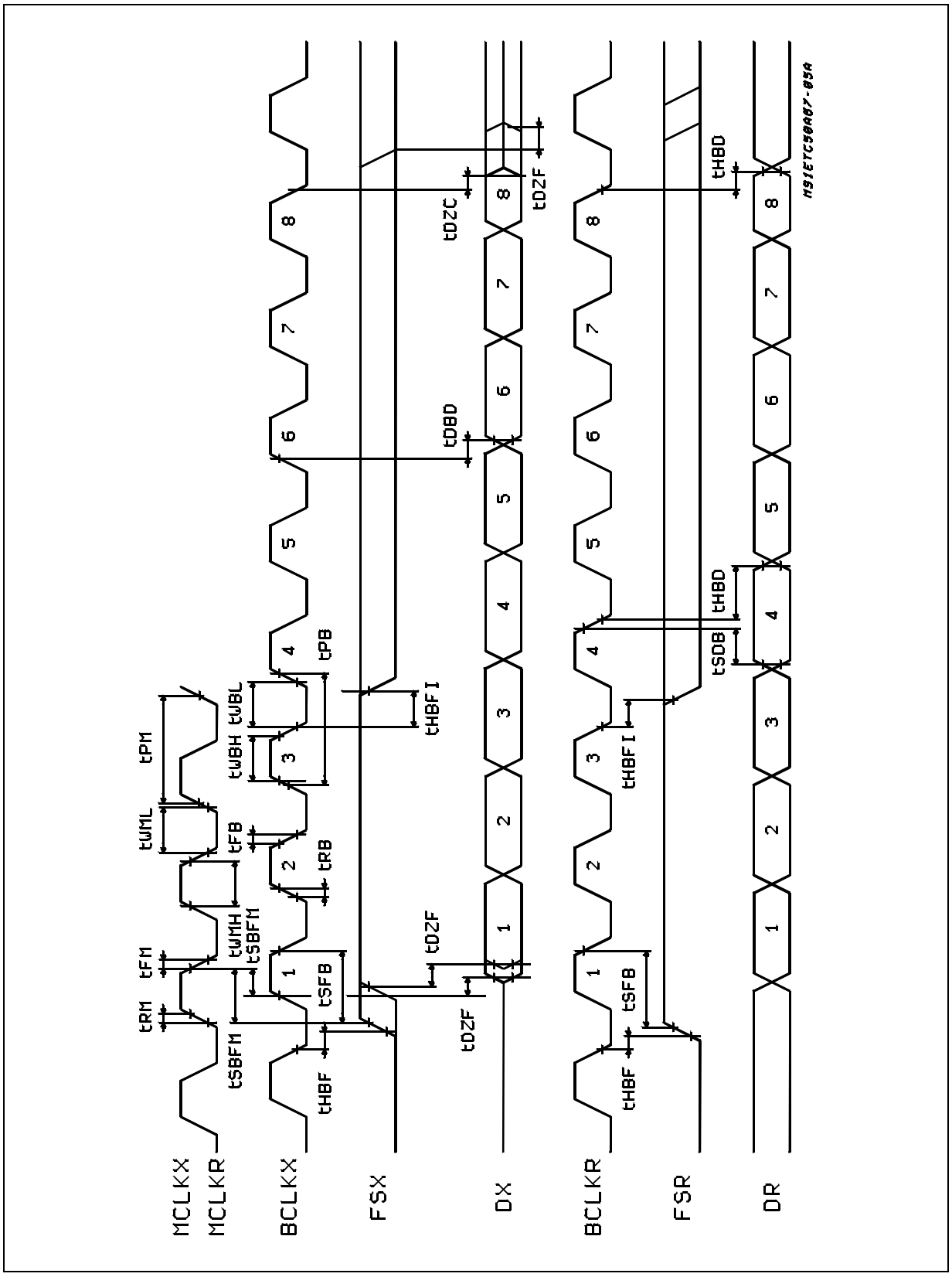


Figure 3 : Long Frame Sync Timing.



TRANSMISSION CHARACTERISTICS

(all devices) T_A = 0°C to 70°C (ETC5064-X/67-X: T_A = –40°C to 85°), V_{CC} = 5V ± 5%, V_{BB} = – 5V ± 5%, GNDA = 0V, f = 1.02kHz, V_{IN} = 0dBm0 transmit input amplifier connected for unity–gain non–inverting. (unless otherwise specified).

AMPLITUDE RESPONSE

Symbol	Parameter	Min.	Typ.	Max.	Unit
	Absolute Levels - Nominal 0 dBm0 is 4 dBm (600Ω). 0 dBm0		1.2276		Vrms
t_{MAX}	Max Overload Level 3.14 dBm0 **ETC5067** 3.17 dBm0 **ETC5064**		 2.492 2.501		VPK
G_{XA}	Transmit Gain, Absolute (T_A = 25°C, V_{CC} = 5V, V_{BB} = -5V) Input at GS_X = 0dBm0 at 1020Hz	-0.15		0.15	dB
GXR	Transmit Gain, Relative to GXA f = 16Hz f = 50Hz f = 60Hz f = 180Hz f = 200Hz f = 300Hz -3000Hz f = 3200Hz (ETC5064-X/67-X) f = 3300Hz f = 3400Hz f = 4000Hz f = 4600Hz and up, measure response from oHz to 4000Hz	 - - - -2.8 -1.8 -0.15 -0.35 -0.35 -0.7		 -40 -30 -26 -0.2 -0.1 0.15 0.20 0.05 0 -14 -32	dB
G_{XAT}	Absolute Transmit Gain Variation with Temperature T_A = 0°C to +70°C T_A = –40°C to +85°C (ETC5064-X/67-X)	 -0.1 -0.15		 0.1 0.15	dB
G_{XAV}	Absolute Transmit Gain Variation with Supply Voltage (V_{CC} = 5V ±5%, V_{BB} = -5V ±5%)	-0.05		0.05	dB
G_{XRL}	Transmit Gain Variation with Level Sinusolidal Test Method Reference Level = -10dBm0 VF_XI^+ = -40dBm0 to +3dBm0 VF_XI^+ = -50dBm0 to -40dBm0 VF_XI^+ = -55dBm0 to -50dBm0	 -0.2 -0.4 -1.2		 0.2 0.4 1.2	dB
G_{RA}	Receive Gain, Absolute (T_A = 25°C, V_{CC} = 5V, V_{BB} = -5V) Input = Digital Code Sequence for 0dBm0 Signal at 1020Hz	-0.15		0.15	dB
G_{RR}	Receive Gain, Relative to G_{RA} f = 0Hz to 3000Hz f = 3200Hz (ETC5064-X/67-X) f = 3300Hz f = 3400Hz f = 4000Hz	 -0.15 -0.35 -0.35 -0.7		 0.15 0.20 0.05 0 -14	dB
G_{RAT}	Absolute Receive Gain Variation with Temeperature T_A = 0°C to +70°C T_A = –40°C to +85°C (ETC5064-X/67-X)	 -0.1 -0.15		 0.1 0.15	dB
G_{RAV}	Absolute Receive Gain Variation with Supply Voltage (V_{CC} = 5V ±5%, V_{BB} = -5V ±5%)	-0.05		0.05	dB
G_{RRL}	Receive Gain Variation with Level Sinusoidal Test Method; Reference Input PCM code corresponds to an ideally encoded -10dBm0 signal PCM level = -40dBm0 to +3dBm0 PCM level = -50dBm0 to -40dBm0 PCM level = -55dBm0 to -50dBm0	 -0.2 -0.4 -1.2		 0.2 0.4 1.2	dB
V_{RO}	Receive Filter Output at VF_RO R_L = 10KΩ	-2.5		2.5	V

TRANSMISSION CHARACTERISTICS (continued).

ENVELOPE DELAY DISTORTION WITH FREQUENCY

Symbol	Parameter	Min.	Typ.	Max.	Unit
D_{XA}	Transmit Delay, Absolute (f = 1600 Hz)		290	315	µs
D_{XR}	Transmit Delay, Relative to D_{XA}				
	f = 500 Hz-600 Hz		195	220	
	f = 600 Hz-800 Hz		120	145	
	f = 800 Hz-1000 Hz		50	75	µs
	f = 1000 Hz-1600 Hz		20	40	
	f = 1600 Hz-2600Hz		55	75	
	f = 2600 Hz-2800 Hz		80	105	
	f = 2800 Hz-3000 Hz		130	155	
D_{RA}	Receive Delay, Absolute (f = 1600 Hz)		180	200	µs
D_{RR}	Receive Delay, Relative to D_{RA}				
	f = 500 Hz-1000 Hz	– 40	– 25		
	f = 1000 Hz-1600 Hz	– 30	– 20		µs
	f = 1600 Hz-2600 Hz		70	90	
	f = 2600 Hz-2800 Hz		100	125	
	f = 2800 Hz-3000 Hz		145	175	

NOISE

Symbol	Parameter	Min.	Typ.	Max.	Unit
N_{XP}	Transmit Noise, P Message (A-LAW, VF_XI^+ = 0 V) Weighted 1)				
	ETC5064		– 74	– 69	dBm0p
	ETC5064-X		– 74	– 67	dBm0p
N_{RP}	Receive Noise, P Message Weighted (A-LAW, PCM Code Equals Positive Zero)		– 82	– 79	dBm0p
N_{XC}	Transmit Noise, C Message Weighted				
	(µ-LAW, $VFxI^+$ = 0 V) **ETC5064**		12	15	dBrnC0
	ETC5064-X		12	16	dBrnC0
N_{RC}	Receive Noise, C Message Weighted (µ-LAW, PCM Code Equals Alternating Positive and Negative Zero)		8	11	dBrnC0
N_{RS}	Noise, Single Frequency f = 0 kHz to 100 kHz, Loop around Measurement, VF_XI^+ = 0 V			– 53	dBm0
$PPSR_X$	Positive Power Supply Rejection, Transmit (note 2) V_{CC} = 5.0 V_{DC} + 100 mVrms, f = 0 kHz-50 kHz	40			dBp
$NPSR_X$	Negative Power Supply Rejection, Transmit (note 2) V_{BB} = 5.0 V_{DC} + 100 mVrms, f = 0 kHz-50 kHz	40			dBp
$PPSR_R$	Positive Power Supply Rejection, Receive (PCM code equals positive zero, V_{CC} = 5.0 V_{DC} + 100 mVrms)				
	f = 0 Hz-4000Hz A LAW	40			dBp
	µ LAW	40			dBc
	f = 4 kHz-25 kHz	40			dB
	f = 25 kHz-50 kHz	36			dB
$NPSR_R$	Negative Power Supply Rejection, Receive (PCM code equals positive zero, V_{BB} = – 5.0 V_{DC} + 100 mVrms)				
	f = 0 Hz-4000Hz A LAW	40			dBp
	µ LAW	40			dBc
	f = 4 kHz-25 kHz	40			dB
	f = 25 kHz-50 kHz	36			dB
SOS	Spurious out-of-band Signals at the Channel Output 0 dBm0, 300 Hz-3400 Hz input PCM applied at D_R				
	4600 Hz-7600 Hz			–32	dB
	7600 Hz-8400 Hz			–40	dB
	8400 Hz-100,000 Hz			–32	dB

TRANSMISSION CHARACTERISTICS (continued).

DISTORTION

Symbol	Parameter		Min.	Typ.	Max.	Unit
STD_X or STD_R	Signal to Total Distortion (sinusoidal test method) Transmit or Receive Half-channel					dBp
	Level = 3.0 dBm0		33			(ALAW)
	= 0 dBm0 to – 30 dBm0		36			
	= – 40 dBm0	XMT	29			dBc
		RCV	30			(μLAW)
	= – 55 dBm0	XMT	14			
		RCV	15			
SFD_X	Single Frequency Distortion, Transmit (T_A = 25°C)				– 46	dB
SFD_R	Single Frequency Distortion, Receive (T_A = 25°C)				– 46	dB
IMD	Intermodulation Distortion Loop Around Measurement, VF_XI^+ = – 4 dBm0 to – 21 dBm0, two Frequencies in the Range 300 Hz-3400 Hz				– 41	dB

CROSSTALK

Symbol	Parameter		Min.	Typ.	Max.	Unit
CT_{X-R}	Transmit to Receive Crosstalk, 0dBm0 Transmit f = 300 Hz-3400 Hz, D_R = Steady PCM Code	**ETC5064/67**		– 90	– 75	dB
		ETC5064-X/67-X			– 65	dB
CT_{R-X}	Receive to Transmit Crosstalk, 0dBm0 Receive Level (note 2) f = 300 Hz-3400 Hz, VF_XI = 0 V	**ETC5064/67**		– 90	– 70	dB
		ETC5064-X/67-X			– 65	dB

POWER AMPLIFIERS

Symbol	Parameter	Min.	Typ.	Max.	Unit
V_{OL}	Maximum 0 dBm0 Level for Better than ± 0.1 dB Linearity Over the Range 10 dBm0 to + 3 dBm0 (balanced load, R_L connected between VPO^+ and VPO^-)				Vrms
	R_L = 600 Ω	33			
	R_L = 1200 Ω	3.5			
	R_L = 30 kΩ	4.0			
S/D_P	Signal/Distortion R_L = 600 Ω, 0 dBm0	50			dB

Notes : 1. Measured by extrapolation from the distortion test results.
2. PPSRX, NPSRX, CTR–X measured with a –50dBm0 activating signal applied at VF_XI^+

ENCODING FORMAT AT D_X OUTPUT

	A-Law (Including even bit inversion)	μLaw
V_{IN} (at GS_X) = + Full-scale	1 0 1 0 1 0 1 0	1 0 0 0 0 0 0 0
V_{IN} (at GS_X) = 0 V	1 1 0 1 0 1 0 1 0 1 0 1 0 1 0 1	1 1 1 1 1 1 1 1 0 1 1 1 1 1 1 1
V_{IN} (at GS_X) = – Full-scale	0 0 1 0 1 0 1 0	0 0 0 0 0 0 0 0

APPLICATION INFORMATION

POWER SUPPLIES

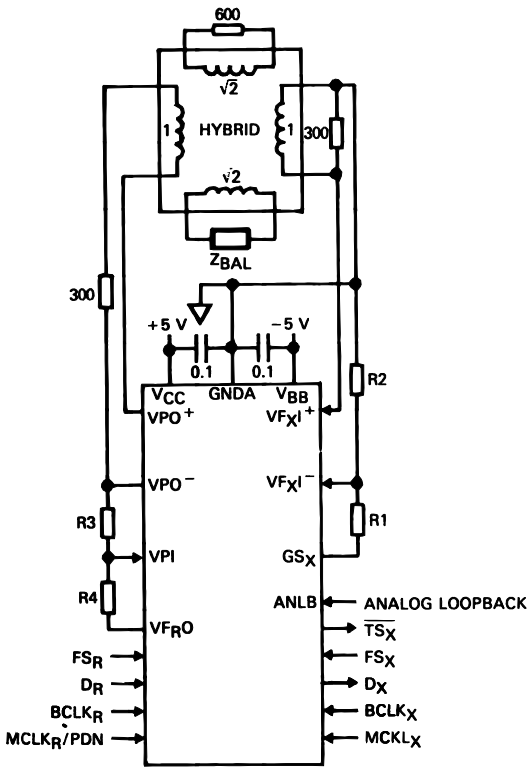
While the pins at the ETC506X family are well protected against electrical misure, it is recommended that the standard CMOS practice be followed, ensuring that ground is connected to the device before any other connections are made. In applications where the printed circuit board may be plugged into a "hot" socket with power and clocks already present, an extra long ground pin in the connector should be used.

All ground connections to each device should meet at a common point as close as possible to the GNDA pin. This minimizes the interaction of ground return currents flowing through a common bus impedance. 0.1µF supply decoupling capacitors should be connected from this common ground point to VCC and VBB as close to the device as possible.

For best performance, the ground point of each CODEC/FILTER on a card should be connected to a common card ground in star formation, rather than via a ground bus. This common ground point should be decoupled to VCC and VBB with 10µF capacitors.

For best performance, $\overline{TSx}$ should be grounded if not used.

Figure 4 : Typical Asynchronous Application.

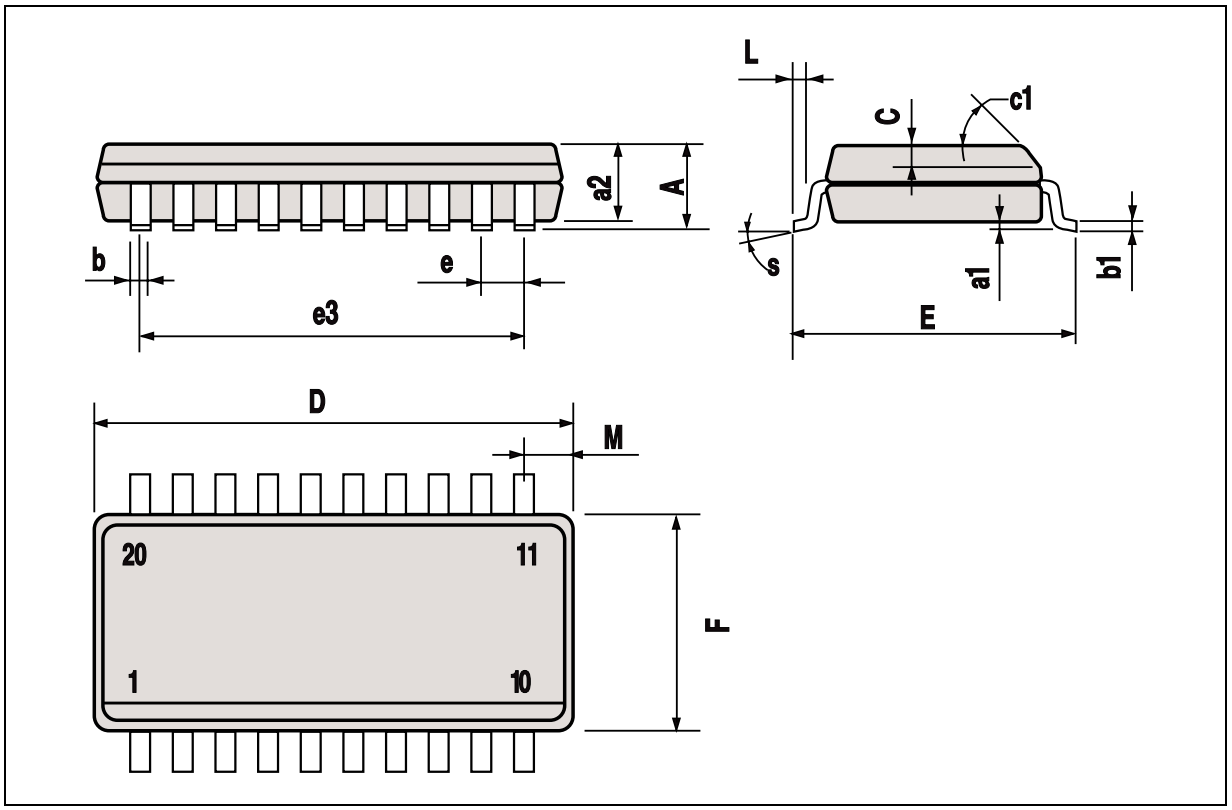


Note 1 : Transmit gain $= 20 \times \log\left(\frac{R1 + R2}{R2}\right)$, $(R1 + R2) \geq 10\ k\Omega$

Note 2 : Receive gain $= 20 \times \log\left(\frac{2 \times R3}{R4}\right)$, $R4 \geq 10\ k\Omega$

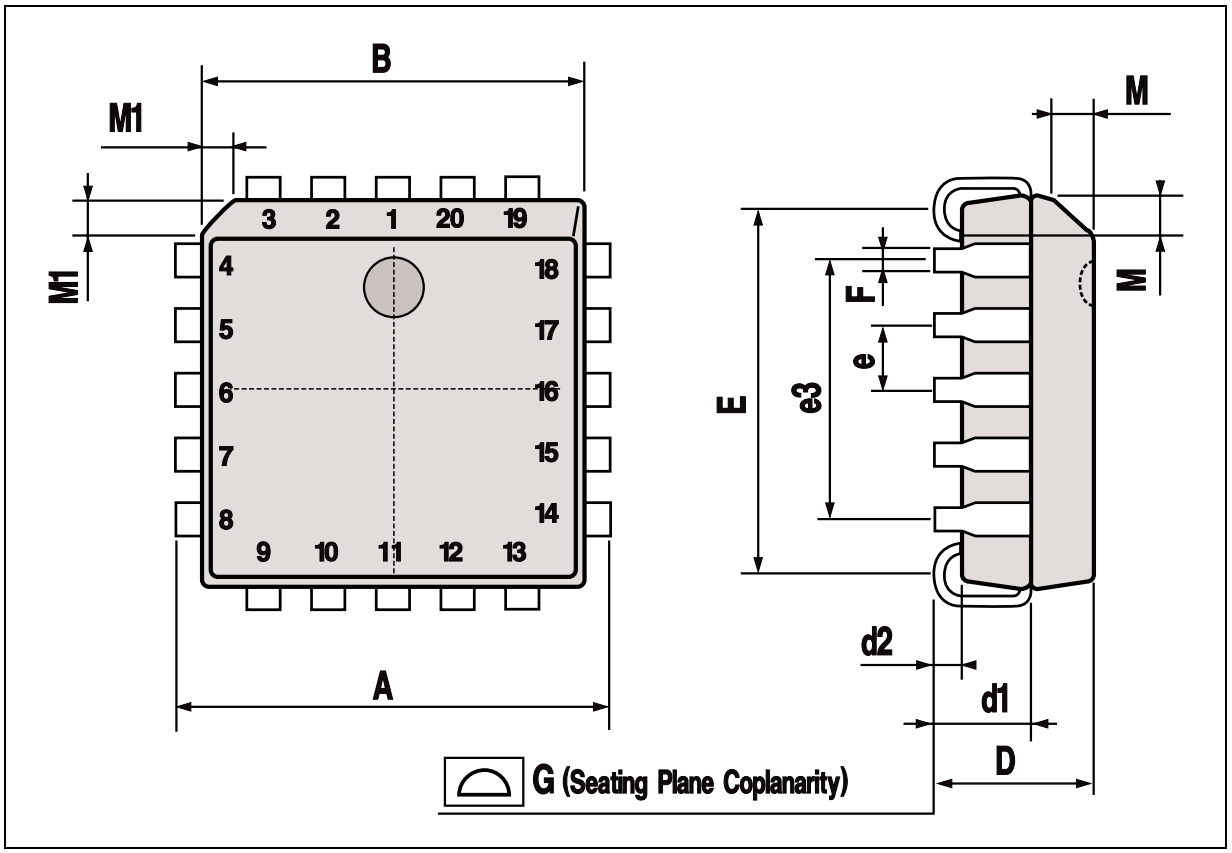
SO20 PACKAGE MECHANICAL DATA

DIM.	mm			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A			2.65			0.104
a1	0.1		0.2	0.004		0.008
a2			2.45			0.096
b	0.35		0.49	0.014		0.019
b1	0.23		0.32	0.009		0.013
C		0.5			0.020	
c1	45° (typ.)					
D	12.6		13.0	0.496		0.510
E	10		10.65	0.394		0.419
e		1.27			0.050	
e3		11.43			0.450	
F	7.4		7.6	0.291		0.300
L	0.5		1.27	0.020		0.050
M			0.75			0.030
S	8° (max.)					



PLCC20 PACKAGE MECHANICAL DATA

DIM.	mm			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A	9.78		10.03	0.385		0.395
B	8.89		9.04	0.350		0.356
D	4.2		4.57	0.165		0.180
d1		2.54			0.100	
d2		0.56			0.022	
E	7.37		8.38	0.290		0.330
e		1.27			0.050	
e3		5.08			0.200	
F		0.38			0.015	
G			0.101			0.004
M		1.27			0.050	
M1		1.14			0.045	



DIP20 PACKAGE MECHANICAL DATA

DIM.	mm			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
a1	0.254			0.010		
B	1.39		1.65	0.055		0.065
b		0.45			0.018	
b1		0.25			0.010	
D			25.4			1.000
E		8.5			0.335	
e		2.54			0.100	
e3		22.86			0.900	
F			7.1			0.280
I			3.93			0.155
L		3.3			0.130	
Z			1.34			0.053